

IN THE ABSTRACT:

Please substitute the following Substitute Abstract for the originally filed Abstract as follows:

Substitute Abstract

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An electrostatic chucking device having a laminated structure formed by sequentially laminating a first insulation layer, an electrode layer, and a second insulation layer on a metal substrate. The first and second insulation layers are formed from polyimide films. At least one adhesion layer is provided between the metal substrate and the first insulation layer, and, preferably, between the first insulation layer and the electrode layer, and between the electrode layer and the second insulation layer. The adhesion layer is a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μ m. The electrostatic chucking device may be manufactured by a low-temperature compression bonding process under pressure at a temperature of 100 to 250°C between the metal substrate and the first insulation layer, between the first insulation layer and the electrode layer, and between the electrode layer and the second insulation layer using thermoplastic polyimide-based adhesion films.